

Description

PECJ P-channel Enhancement Mode Power MOSFET

Features

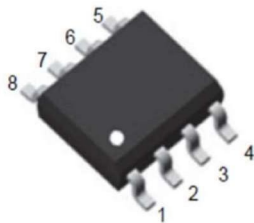
- $V_{DS} = -30V$, $I_D = -15A$
 $R_{DS(ON)} < 9m\Omega @ V_{GS} = -10V$
 $R_{DS(ON)} < 14m\Omega @ V_{GS} = -4.5V$
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead free product is acquired

Application

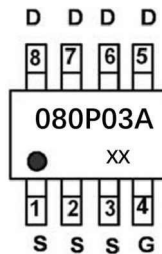
- PWM Applications
- Load Switch
- Power Management



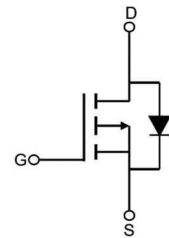
100% UIS TESTED!
100% ΔVds TESTED!



SOP-8 top view



Marking and pin Assignment



Schematic Diagram

Package Marking and Ordering Information

| Device Marking | Device | OUTLINE | Device Package | Reel Size | Reel (PCS) | Per Carton (PCS) |
|----------------|--------------|---------|----------------|-----------|------------|------------------|
| 080P03A | PECJP080P03A | TAPING | SOP-8 | 13inch | 4000 | 48000 |

Absolute Maximum Ratings ($T_A = 25^\circ C$ unless otherwise specified)

| Symbol | Parameter | Max. | Units |
|-----------------|---|---------------------|--------------|
| V_{DSS} | Drain-Source Voltage | -30 | V |
| V_{GSS} | Gate-Source Voltage | ± 20 | V |
| I_D | Continuous Drain Current | $T_A = 25^\circ C$ | -15 |
| | | $T_A = 100^\circ C$ | -10 |
| I_{DM} | Pulsed Drain Current <small>note1</small> | -60 | A |
| E_{AS} | Single Pulsed Avalanche Energy <small>note2</small> | 105 | mJ |
| P_D | Power Dissipation | 3 | W |
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient | 42.6 | $^\circ C/W$ |
| T_J, T_{STG} | Operating and Storage Temperature Range | -55 to +150 | $^\circ C$ |

Electrical Characteristics (T_J=25°C unless otherwise specified)

| Symbol | Parameter | Test Condition | Min. | Typ. | Max. | Units |
|---|---|--|------|------|------|-------|
| Off Characteristic | | | | | | |
| V _{(BR)DSS} | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D = -250μA | -30 | - | - | V |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} = -30V, V _{GS} =0V, | - | - | -1 | μA |
| I _{GSS} | Gate to Body Leakage Current | V _{DS} =0V, V _{GS} = ±20V | - | - | ±100 | nA |
| On Characteristics | | | | | | |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _D = -250μA | -1.0 | -1.5 | -2.5 | V |
| R _{DS(on)} | Static Drain-Source on-Resistance <small>note3</small> | V _{GS} = -10V, I _D = -15A | - | 7 | 9 | mΩ |
| | | V _{GS} = -4.5V, I _D = -10A | - | 10 | 14 | |
| Dynamic Characteristics | | | | | | |
| C _{iss} | Input Capacitance | V _{DS} = -15V, V _{GS} =0V, f=1.0MHz | - | 4650 | - | pF |
| C _{oss} | Output Capacitance | | - | 550 | - | pF |
| C _{rss} | Reverse Transfer Capacitance | | - | 486 | - | pF |
| Q _g | Total Gate Charge | V _{DS} = -15V, I _D = -10A, V _{GS} = -10V | - | 45 | - | nC |
| Q _{gs} | Gate-Source Charge | | - | 8 | - | nC |
| Q _{gd} | Gate-Drain("Miller") Charge | | - | 12 | - | nC |
| Switching Characteristics | | | | | | |
| t _{d(on)} | Turn-on Delay Time | V _{DD} = -15V, I _D = -15A, V _{GS} = -10V, R _{GEN} =2.5Ω | - | 19 | - | ns |
| t _r | Turn-on Rise Time | | - | 15 | - | ns |
| t _{d(off)} | Turn-off Delay Time | | - | 65 | - | ns |
| t _f | Turn-off Fall Time | | - | 36 | - | ns |
| Drain-Source Diode Characteristics and Maximum Ratings | | | | | | |
| I _S | Maximum Continuous Drain to Source Diode Forward Current | | - | - | -15 | A |
| I _{SM} | Maximum Pulsed Drain to Source Diode Forward Current | | - | - | -60 | A |
| V _{SD} | Drain to Source Diode Forward Voltage | V _{GS} =0V, I _S = -15A | - | -0.8 | -1.2 | V |

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. E_{AS} condition: T_J=25°C, V_{DD}= -15V, V_G= -10V, R_G=25Ω, L=0.5mH, I_{AS}= -20.5A

3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤2%

Typical Performance Characteristics

Figure 1: Output Characteristics

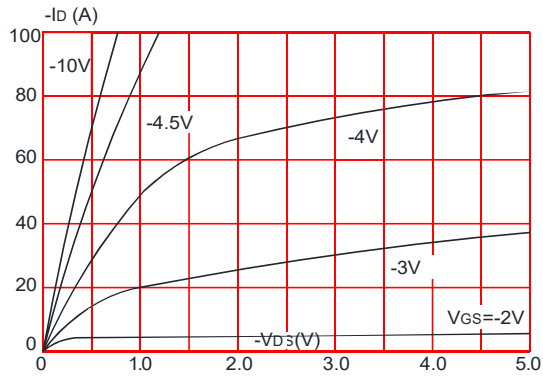


Figure 2: Typical Transfer Characteristics

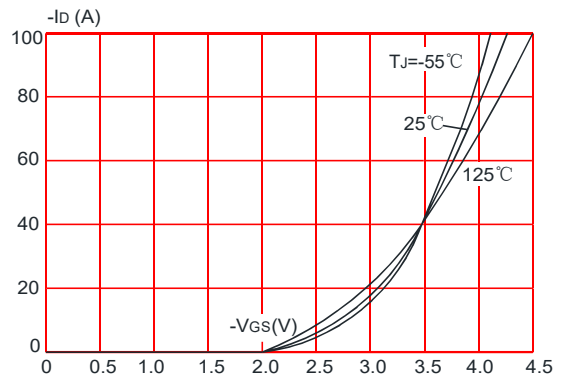


Figure 3: On-resistance vs. Drain Current

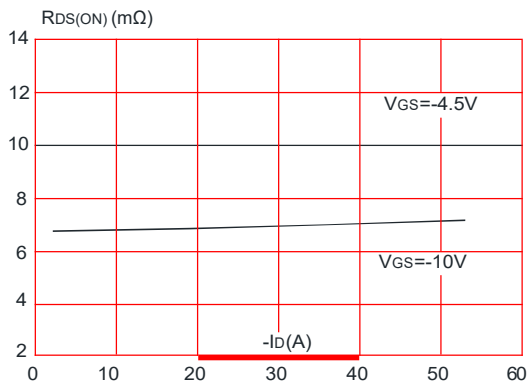


Figure 4: Body Diode Characteristics

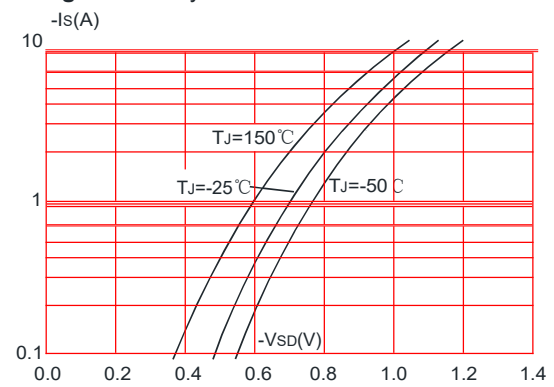


Figure 5: Gate Charge Characteristics

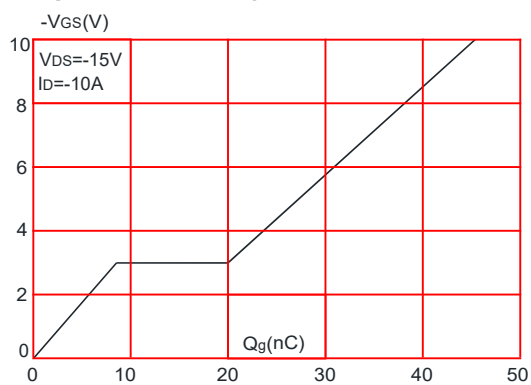


Figure 6: Capacitance Characteristics

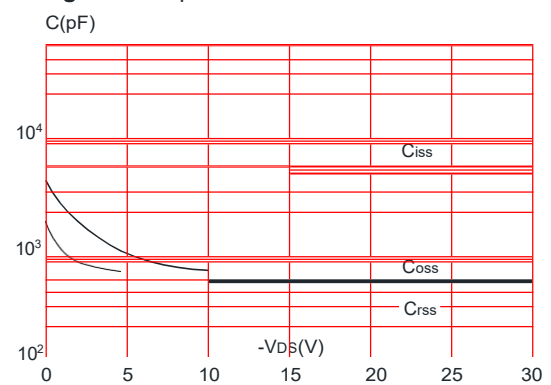


Figure 7: Normalized Breakdown Voltage vs. Junction Temperature

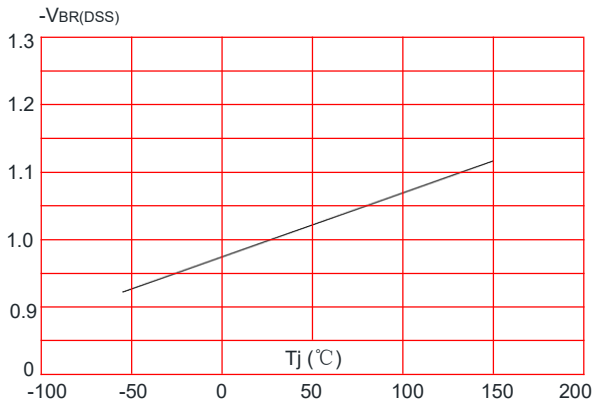


Figure 8: Normalized on Resistance vs. Junction Temperature

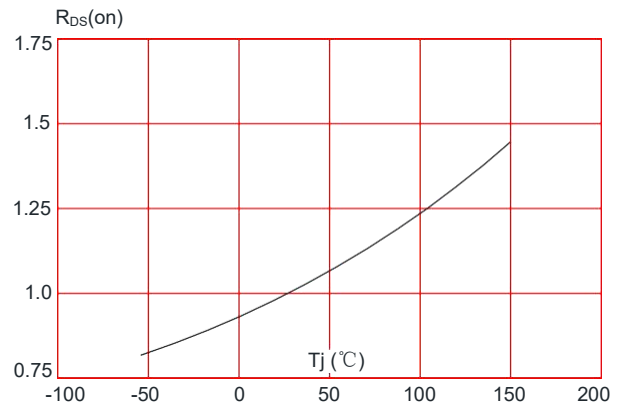


Figure 9: Maximum Safe Operating Area

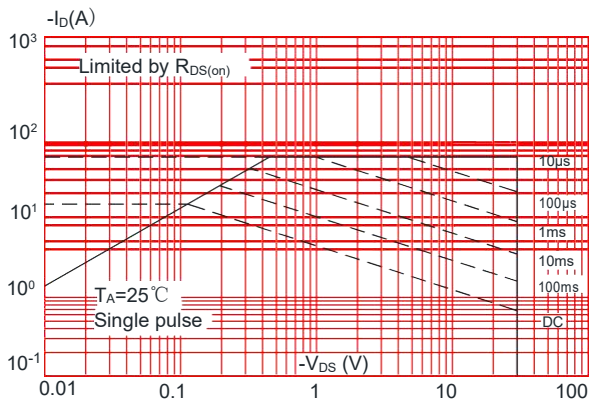


Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature

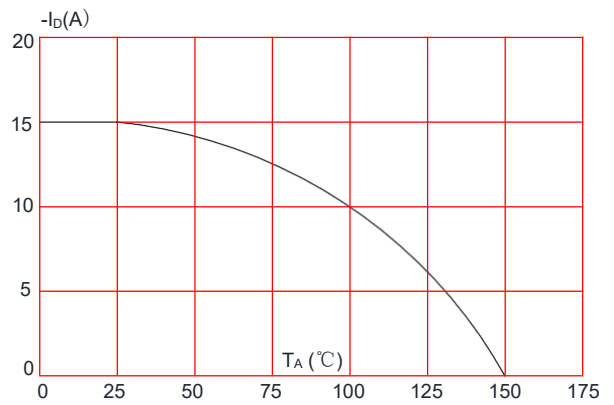
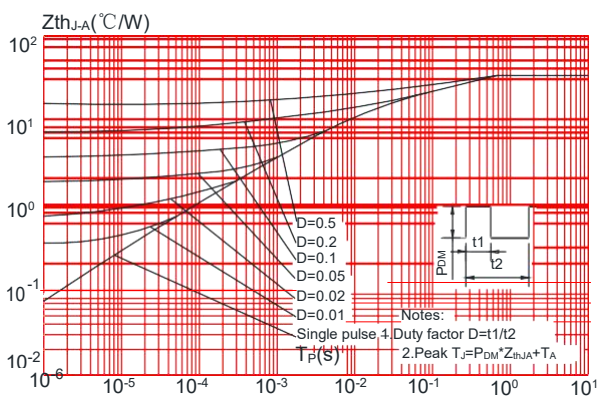
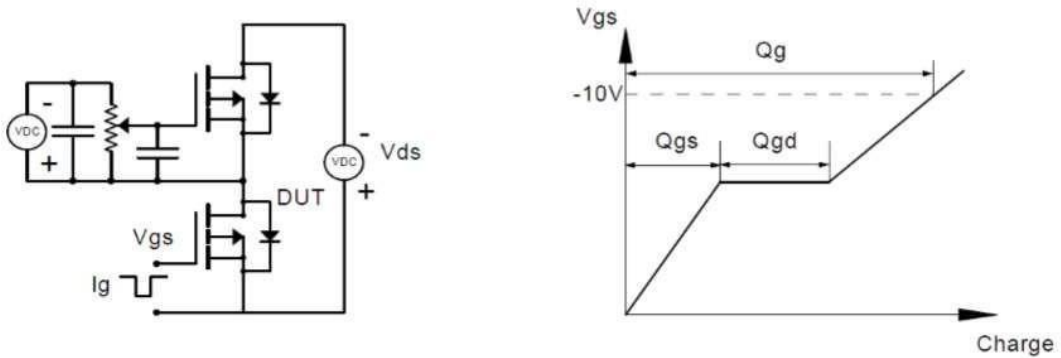


Figure.11: Maximum Effective Transient Thermal Impedance, Junction-to-Ambient

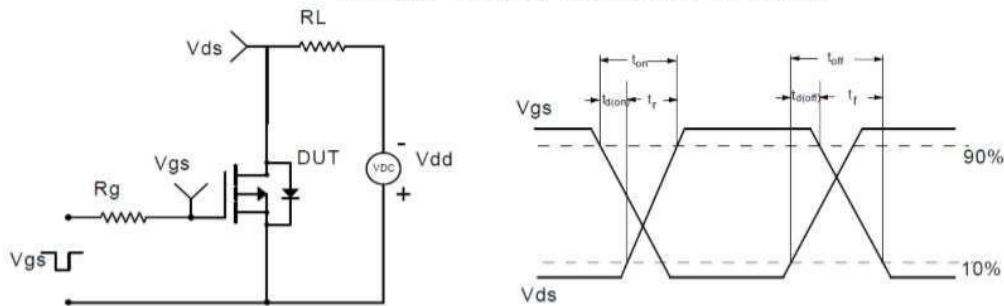


Test Circuit

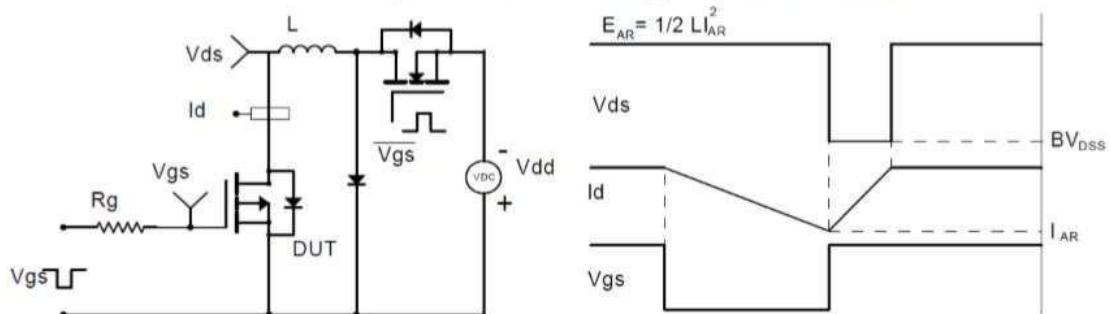
Gate Charge Test Circuit & Waveform



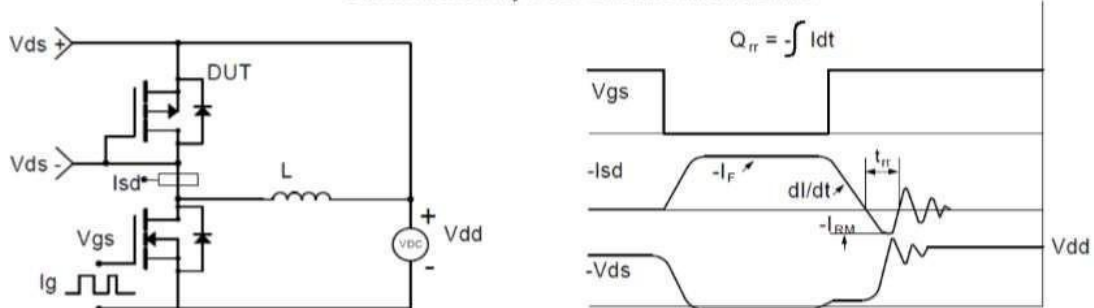
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms



Diode Recovery Test Circuit & Waveforms



Package Mechanical Data- SOP-8

